

17621 U.S.PTO
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Page 1

PATENT

Docket No.: JCLA8533-D2

Date: January 09, 2004

COMMISSIONER FOR PATENTS
P.O. BOX 1450
ALEXANDRIA, VA 22313-1450

ATTENTION: APPLICATION BRANCH

Sir:

This is a request for filing a continuation application under 37 CFR 1.53 (b) as a divisional application of prior application No.10/055,568 filed on January 22, 2002.

Prior application information: Examiner: MITCHELL, JAMES M. ; Group Art Unit: 2827

The entire disclosure of the prior application, from which an oath or declaration is supplied herewith as indicated below, is considered a part of the disclosure of the accompanying continuation or divisional application and is hereby incorporated by reference.

Transmitted herewith for filing is the patent application of

Inventor(s): MOU-SHIUNG LIN ;

JIN-YUAN LEE ;

CHING-CHENG HUENG ;

For: INTEGRATED CHIP PACKAGE STRUCTURE USING SILICON SUBSTRATE AND METHOD OF MANUFACTURING THE SAME

Enclosed are:

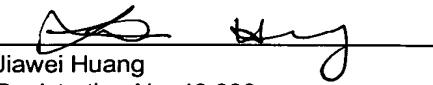
- (X) Specification in FOURTY-ONE (41) pages.
(X) SIXTEEN (16) sheets of Drawings.
(X) Preliminary Amendment.
(X) A copy of Declaration and Power of Attorney from the prior application is enclosed.
(X) Applicant claims small entity status. See 37 CFR 1.27.
(X) Return prepaid postcard.

CLAIMS AS FILED

FOR	NUMBER FILED	NUMBER EXTRA	RATE	FEE
Basic Fee			\$ 385	\$ 385
Total Claims	27 - 20 =	7 x	\$ 9	\$ 63
Independent Claims	1 - 3 =	0 x	\$ 43	\$ 0
If application contains any multiple dependent claims(s), then add			\$ 145	\$ 0
For a Small Entity:	TOTAL FILING FEE			\$ 448

- (X) A check in the amount of \$ 448 to cover the filing fee is enclosed.
(X) The commissioner is authorized to charge any additional necessary fee to Account No. 50-0710 (Order No. JCLA8533-D2). A duplicate copy of this sheet is enclosed.

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CERTIFICATE OF MAILING BY "EXPRESS MAIL"

Docket No. : JCLA8533-D2
Inventor(s) : MOU-SHIUNG LIN ;
JIN-YUAN LEE ;
CHING-CHENG HUENG ;

For : INTEGRATED CHIP PACKAGE STRUCTURE USING SILICON
SUBSTRATE AND METHOD OF MANUFACTURING THE
SAME

"Express Mail"
Mailing Label No. : EV 300987573 US

Date of Deposit : January 09, 2004

I hereby certify that the accompanying

Transmittal in Duplicate; Specification in 41 page(s); 16 sheets of
drawing(s); Copy of Declaration and Power of Attorney from prior
application; Preliminary Amendment; Checks for Filing Fee(s); Return
Prepaid Postcard

are being deposited with the United States Postal Service "Express Mail Post Office to
Addressee" service under 37 CFR 1.10 on the date indicated above and are
addressed to the Commissioner for Patents, P.O. BOX 1450, Alexandria, VA 22313-
1450



Michelle Chang